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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/668,216	09/24/2003	Yasuhiro Yoneda	1422-0603P	1568
	7590 07/10/200 ART KOLASCH & BI	EXAMINER		
PO BOX 747			MARCHESCHI, MICHAEL A	
FALLS CHURCH, VA 22040-0747		•	ART UNIT	PAPER NUMBER
			1755 .	
		•	<u></u>	
•	•		NOTIFICATION DATE	DELIVERY MODE
			07/10/2007	ELECTRONIC

## Please find below and/or attached an Office communication concerning this application or proceeding.

The time period for reply, if any, is set in the attached communication.

Notice of the Office communication was sent electronically on above-indicated "Notification Date" to the following e-mail address(es):

mailroom@bskb.com

		Application No.	Applicant(s)
Office Action Summary		10/668,216	YONEDA ET AL.
		Examiner	Art Unit
		Michael A. Marcheschi	1755
Period fo	The MAILING DATE of this communication app	ears on the cover sheet with the	correspondence address
A SH THE - Exte after - If the - If NO - Failu Any	CORTENED STATUTORY PERIOD FOR REPLY MAILING DATE OF THIS COMMUNICATION.  Insions of time may be available under the provisions of 37 CFR 1.13 SIX (6) MONTHS from the mailing date of this communication.  In SIX (6) MONTHS from the mailing date of this communication.  In Provided For Provided	36(a). In no event, however, may a reply be to within the statutory minimum of thirty (30) da will apply and will expire SIX (6) MONTHS from a cause the application to become ABANDON	imely filed  ys will be considered timely.  In the mailing date of this communication.  ED (35 U.S.C. § 133).
Status			
	·	action is non-final.  nce except for formal matters, pr	
Disposit	ion of Claims		•
5)□ 6)⊠ 7)□	Claim(s) 1-10 is/are pending in the application.  4a) Of the above claim(s) is/are withdraw Claim(s) is/are allowed.  Claim(s) 1-10 is/are rejected.  Claim(s) is/are objected to.  Claim(s) are subject to restriction and/or	vn from consideration.	
Applicati	ion Papers	•	•
10)	The specification is objected to by the Examine The drawing(s) filed on is/are: a) access Applicant may not request that any objection to the Replacement drawing sheet(s) including the correction of the oath or declaration is objected to by the Examine The oath or declaration is objected to by the Examine The specification is objected to by the Examine The oath or declaration is objected to by the Examine The oath or declaration is objected to by the Examine The oath or declaration is objected to by the Examine The oath or declaration is objected to by the Examine The oath or declaration is objected to by the Examine The oath or declaration is objected to by the Examine The oath or declaration is objected to by the Examine The oath or declaration is objected to by the Examine The oath or declaration is objected to by the Examine The oath or declaration is objected to by the Examine The oath or declaration is objected to by the Examine The oath or declaration is objected to by the Examine The oath or declaration is objected to by the Examine The oath or declaration is objected to by the Examine The oath or declaration is objected to by the Examine The oath or declaration is objected to by the Examine The oath or declaration is objected to be a constant.	epted or b) objected to by the drawing(s) be held in abeyance. Se ion is required if the drawing(s) is ol	ee 37 CFR 1.85(a). Djected to. See 37 CFR 1.121(d).
Priority ι	under 35 U.S.C. § 119		
a)[	Acknowledgment is made of a claim for foreign  All b) Some * c) None of:  1. Certified copies of the priority documents  2. Certified copies of the priority documents  3. Copies of the certified copies of the priority application from the International Bureau  See the attached detailed Office action for a list of	s have been received. s have been received in Applicatity documents have been received (PCT Rule 17.2(a)).	tion No ed in this National Stage
2) 🔲 Notic 3) 🔲 Inforr	t(s)  te of References Cited (PTO-892)  te of Draftsperson's Patent Drawing Review (PTO-948)  mation Disclosure Statement(s) (PTO-1449 or PTO/SB/08)  r No(s)/Mail Date	4) Interview Summary Paper No(s)/Mail D 5) Notice of Informal I 6) Other:	

Application/Control Number: 10/668,216

Art Unit: 1755

A request for continued examination under 37 CFR 1.114, including the fee set forth in 37 CFR 1.17(e), was filed in this application after final rejection. Since this application is eligible for continued examination under 37 CFR 1.114, and the fee set forth in 37 CFR 1.17(e) has been timely paid, the finality of the previous Office action has been withdrawn pursuant to 37 CFR 1.114. Applicant's submission filed on 4/30/07 has been entered.

The text of those sections of Title 35, U.S. Code not included in this action can be found in a prior Office action.

Claims 1-10 are rejected under 35 U.S.C. 103(a) as being obvious over EP 1 020 501 in view of Liu et al. and/or Ina et al. and further in view of Taira et al. (216).

The EP reference teaches in sections [0047]-[0057], a polishing slurry for a semiconductor or other substrates (silicon, silicon dioxide or a Ni-P plated aluminum alloy substrate (see section [0077], [0091] and [0094]), comprising a combination of inorganic particles (silica, etc.) and polymer particles (thermoplastic resin). The polymer particles and inorganic particles have a size of at least 0.01 um and the inorganic particles are smaller than the polymer particles. The ratio of the mean particle size of the polymer particles to the mean particle size of the inorganic particles is also defined.

Liu et al. teach in column 6, lines 62+ beneficial reasons to use colloidal abrasives.

Ina et al. teach in column 8, lines 54+ beneficial reasons to use colloidal abrasives.

Taira et al. (216) teaches in column 11, lines 1-18, that polishing composition are known to have a pH of 2-12 (for any substrate) and said pH is dependent on the substrate to be polished.

Art Unit: 1755

It is further stated that when semiconductors are polished, the pH of a polishing composition is known to be preferably 7-12.

The primary reference teaches a polishing slurry (bi-modal) which reads on the instant claims in view of the teaching of the individual particle sizes and the ratio of the mean particle size of the polymer particles to the mean particle size of the inorganic particles. The size ranges disclosed by the primary reference encompasses values which meet the claimed formula. In view of this, the claimed formula and therefore subject matter of claims 1, 2, 4, and 7-10 would have been obvious to one having ordinary skill in the art at the time the invention was made to have selected the overlapping portion of the range disclosed by the reference because overlapping ranges have been held to be a prima facie case of obviousness, see In re Malagari, 182 U.S.P.Q. 549; In re Wertheim 191 USPQ 90 (CCPA 1976). With respect to the colloidal silica limitation, the use of colloidal silica would have been obvious because both Liu et al. and Ina et al. teach beneficial reasons to use this material, thus one skilled in the art would have found it obvious to use this silica form in view of the beneficial reasons defined by these references. With respect to the limitation of claim 3, it is the examiners position that the polymers defined by this reference will have the claimed glass transition temperature absent evidence to the contrary. With respect to the limitations of claim 5, since the particles are independent of one another, they must have the same zeta potential sign. With respect to the limitation of claim 6, the reference defines amounts for the inorganic and organic particles and although a ratio is not specifically defined, the claimed ratio is broadly encompassed by the reference defining a mixture. Finally, with respect to the pH, the primary reference states that the composition is used to polish semiconductor substrate and since it is known that the pH of the

composition is dependent on the substrate to be polished (see page 18, lines 12+ of the instant specification and the teachings in Taira et al. in column 11, lines 1-4), one skilled in the art would have appreciated and thus found the claimed pH obvious in the composition according to EP 1 020 501 because polishing compositions for semiconductors are known to have this pH, as shown by Taira et al. With respect to the pH of the composition for polishing aluminum alloy substrate plated with Ni-P, Taira et al. defines that the pH of a polishing composition for this can be 2-12, thus one skilled in the art would have appreciated and thus found the claimed pH obvious in the composition according to EP 1 020 501 because polishing compositions for this material are known to have this pH, as shown by Taira et al. The EP reference does not define a pH, thus the skilled artisan would appreciated that the composition can be made to have any known pH value for the applications sought.

Applicant's arguments with respect to all the claims have been considered but are moot in view of the new ground(s) of rejection.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Michael A. Marcheschi whose telephone number is (571) 272-1374. The examiner can normally be reached on M-F (8:00-5:30) First Friday Off.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Jerry Lorengo can be reached on (571) 272-1233. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Application/Control Number: 10/668,216

Art Unit: 1755

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

5/07 MM Michael A Marcheschi Primary Examiner Art Unit 1755 Page 5